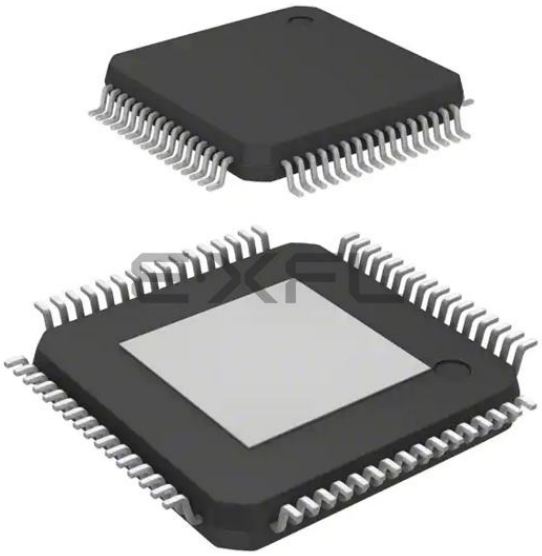
Infineon Technologies - XMC1402F064X0128AAXUMA1 Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	ARM® Cortex®-M0
Core Size	32-Bit Single-Core
Speed	48MHz
Connectivity	I²C, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, I²S, POR, PWM, WDT
Number of I/O	48
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP Exposed Pad
Supplier Device Package	PG-LQFP-64-6
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/xmc1402f064x0128aaxuma1

XMC1400 AA-Step

Microcontroller Series
for Industrial Applications

XMC1000 Family

ARM® Cortex®-M0
32-bit processor core

Data Sheet

V1.3 2016-10

Microcontrollers

Table of Contents

Table 1 Features of XMC1400 Device Types[1)] (cont'd)

Features		XMC1401-Q048	XMC1401-F064	XMC1402-T038	XMC1402-Q040	XMC1402-Q048	XMC1402-Q064	XMC1402-F064	XMC1403-Q040	XMC1403-Q048	XMC1403-Q064	XMC1404-Q048	XMC1404-Q064	XMC1404-F064
Analog	ADC (kernels / analog inputs)	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12	2 / 12
	ACMP	-	-	3	3	4	4	4	-	-	-	4	4	4
GPIOs		34	48	26	27	34	48	48	27	34	48	34	48	48
GPIs		8	8	8	8	8	8	8	8	8	8	8	8	8
Packages		VQFN-48	LQFP-64	TSSOP-38	VQFN-40	VQFN-48	VQFN-64	LQFP-64	VQFN-40	VQFN-48	VQFN-64	VQFN-48	VQFN-64	LQFP-64

1) Features that are not included in this table are available in all the derivatives

1.2 Ordering Information

The ordering code for an Infineon microcontroller provides an exact reference to a specific product. The code "XMC1<DDD>-<Z><PPP><T><FFFF>" identifies:

- <DDD> the derivatives function set
- <Z> the package variant
  - T: TSSOP
  - Q: VQFN
  - F: LQFP
- <PPP> package pin count
- <T> the temperature range:
  - F: -40°C to 85°C
  - X: -40°C to 105°C
- <FFFF> the Flash memory size in Kbytes.

For ordering codes for the XMC1400 please contact your sales representative or local distributor.

This document describes several derivatives of the XMC1400 series, some descriptions may not apply to a specific product. Please see **Table 2**.

For simplicity the term **XMC1400** is used for all derivatives throughout this document.

1.3 Device Types

These device types are available and can be ordered through Infineon's direct and/or distribution channels.

Table 2 Synopsis of XMC1400 Device Types

Derivative	Package	Flash Kbytes
XMC1401-Q048F0064	PG-VQFN-48	64
XMC1401-Q048F0128	PG-VQFN-48	128
XMC1401-F064F0064	PG-LQFP-64	64
XMC1401-F064F0128	PG-LQFP-64	128
XMC1402-T038X0032	PG-TSSOP-38	32
XMC1402-T038X0064	PG-TSSOP-38	64
XMC1402-T038X0128	PG-TSSOP-38	128
XMC1402-T038X0200	PG-TSSOP-38	200
XMC1402-Q040X0032	PG-VQFN-40	32
XMC1402-Q040X0064	PG-VQFN-40	64
XMC1402-Q040X0128	PG-VQFN-40	128
XMC1402-Q040X0200	PG-VQFN-40	200
XMC1402-Q048X0032	PG-VQFN-48	32
XMC1402-Q048X0064	PG-VQFN-48	64
XMC1402-Q048X0128	PG-VQFN-48	128
XMC1402-Q048X0200	PG-VQFN-48	200
XMC1402-Q064X0064	PG-VQFN-64	64
XMC1402-Q064X0128	PG-VQFN-64	128
XMC1402-Q064X0200	PG-VQFN-64	200
XMC1402-F064X0064	PG-LQFP-64	64
XMC1402-F064X0128	PG-LQFP-64	128
XMC1402-F064X0200	PG-LQFP-64	200
XMC1403-Q040X0064	PG-VQFN-40	64
XMC1403-Q040X0128	PG-VQFN-40	128
XMC1403-Q040X0200	PG-VQFN-40	200
XMC1403-Q048X0064	PG-VQFN-48	64
XMC1403-Q048X0128	PG-VQFN-48	128

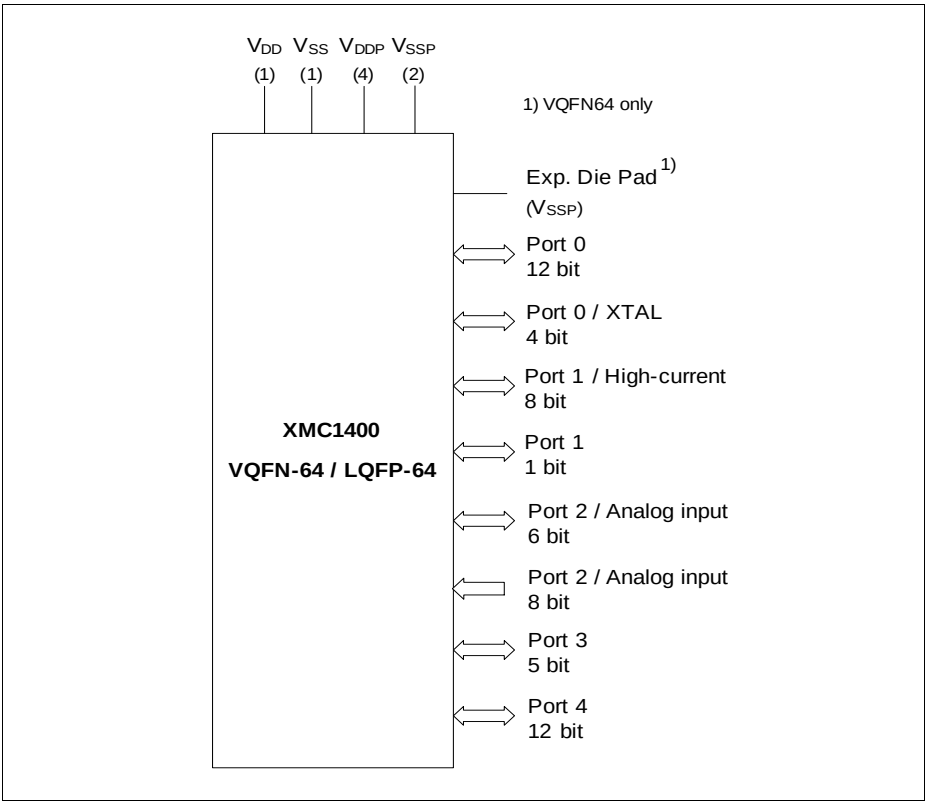


Figure 5 XMC1400 Logic Symbol for PG-LQFP-64-26 / PG-VQFN-64-6

Table 5 Package Pin Mapping (cont'd)

Function	LQFP 64, VQFN 64	VQFN 48	VQFN 40	TSSOP 38	Pad Type	Notes
P0.9/ RTC_ XTAL2	52	40	34	28	STD_INOUT /clock_O	
P0.10/ XTAL1	53	41	35	29	STD_INOUT /clock_IN	
P0.11/ XTAL2	54	42	36	30	STD_INOUT /clock_O	
P0.12	55	43	37	31	STD_INOUT	
P0.13	56	44	38	32	STD_INOUT	
P0.14	57	45	39	33	STD_INOUT	
P0.15	58	46	40	34	STD_INOUT	
P1.0	34	26	22	16	High Current	
P1.1	33	25	21	15	High Current	
P1.2	32	24	20	14	High Current	
P1.3	31	23	19	13	High Current	
P1.4	30	22	18	12	High Current	
P1.5	29	21	17	11	High Current	
P1.6	28	20	16	-	High Current	
P1.7	27	-	-	-	High Current	
P1.8	26	-	-	-	STD_INOUT	
P2.0	9	3	1	35	STD_INOUT /AN	
P2.1	10	4	2	36	STD_INOUT /AN	
P2.2	11	5	3	37	STD_IN/AN	
P2.3	12	6	4	38	STD_IN/AN	
P2.4	13	7	5	1	STD_IN/AN	
P2.5	14	8	6	2	STD_IN/AN	
P2.6	15	9	7	3	STD_IN/AN	
P2.7	16	10	8	4	STD_IN/AN	

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs											
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P2.2										ACMP2.INN	VADC0.G0CH7		ORC0.AIN	USIC1_CH0.DX5E		USIC0_CH0.DX3A	USIC0_CH0.DX4A	USIC0_CH1.DX5A			ERU0.0B1
P2.3												VADC0.G1CH5	ORC1.AIN	USIC1_CH0.DX3E	USIC1_CH0.DX4E	USIC1_CH1.DX5C	USIC0_CH0.DX5B	USIC0_CH1.DX3C	USIC0_CH1.DX4C		ERU0.1B1
P2.4												VADC0.G1CH6	ORC2.AIN	USIC1_CH1.DX3C	USIC1_CH1.DX4C	USIC0_CH0.DX3B	USIC0_CH0.DX4B	USIC1_CH0.DX5F	USIC0_CH1.DX5B		ERU0.0A1
P2.5												VADC0.G1CH7	ORC3.AIN	USIC1_CH1.DX5D		USIC0_CH0.DX5D		USIC0_CH1.DX3E	USIC0_CH1.DX4E		ERU0.1A1
P2.6										ACMP1.INN	VADC0.G0CH0		ORC4.AIN	USIC1_CH1.DX3E	USIC1_CH1.DX4E	USIC0_CH0.DX3E	USIC0_CH0.DX4E	USIC0_CH1.DX5D			ERU0.2A1
P2.7										ACMP1.INP		VADC0.G1CH1	ORC5.AIN	USIC1_CH1.DX5E		USIC0_CH0.DX5C		USIC0_CH1.DX3D	USIC0_CH1.DX4D		ERU0.3A1
P2.8										ACMP0.INN	VADC0.G0CH1	VADC0.G1CH0	ORC6.AIN			USIC0_CH0.DX3D	USIC0_CH0.DX4D	USIC0_CH1.DX5C			ERU0.3B1
P2.9										ACMP0.INP	VADC0.G0CH2	VADC0.G1CH4	ORC7.AIN			USIC0_CH0.DX5A		USIC0_CH1.DX3B	USIC0_CH1.DX4B		ERU0.3B0
P2.10	ERU0.PDOUT1	CCU40.OUT2	ERU0.GOUT1	LEDTS1.COL4	CCU80.OUT30	ACMP0.OUT	USIC0_CH1.DOUT0		CAN.N1_TXD		VADC0.G0CH3	VADC0.G1CH2				USIC0_CH0.DX3C	USIC0_CH0.DX4C	USIC0_CH1.DX0F		CAN.N1_RXDE	ERU0.2B0
P2.11	ERU0.PDOUT0	CCU40.OUT3	ERU0.GOUT0	LEDTS1.COL3	CCU80.OUT31	USIC0_CH1.SCLKOUT	USIC0_CH1.DOUT0		CAN.N1_TXD	ACMP.REF	VADC0.G0CH4	VADC0.G1CH3						USIC0_CH1.DX0E	USIC0_CH1.DX1E	CAN.N1_RXDF	ERU0.2B1
P2.12	BCCU0.OUT3	VADC0.EMUX00	USIC1_CH0.SCLKOUT	USIC1_CH1.SCLKOUT		ACMP2.OUT	USIC1_CH1.DOUT0	LEDTS2.COL6		ACMP3.INN						USIC1_CH0.DX3A	USIC1_CH0.DX4A	USIC1_CH1.DX0C	USIC1_CH1.DX1B		ERU1.3A2
P2.13	BCCU0.OUT4	CCU40.OUT3	USIC1_CH0.MCLKOUT	CCU81.OUT31		VADC0.EMUX01	USIC1_CH1.DOUT0	CCU81.OUT33	CCU41.OUT3	ACMP3.INP						USIC1_CH0.DX5A		USIC1_CH1.DX0D			ERU1.3A3
P3.0	BCCU0.OUT0	USIC1_CH1.DOUT0	USIC1_CH1.SCLKOUT	LEDTS2.COLA	CCU80.OUT21	ACMP1.OUT	USIC1_CH0.SELO1	CCU81.OUT21	CCU41.OUT0	BCCU0.TRAPINC	CCU41.IN0AA	CCU41.IN1AA	CCU41.IN2AA	CCU41.IN3AA	CCU81.IN0AA	CCU81.IN1AA	CCU81.IN2AA	USIC1_CH1.DX0E	USIC1_CH1.DX1D	CCU81.IN3AA	ERU1.0A1
P3.1	BCCU0.OUT1	USIC1_CH1.DOUT0		LEDTS2.COL0	CCU80.OUT20	ACMP3.OUT	USIC1_CH0.SELO0	CCU81.OUT20	CCU41.OUT1								USIC1_CH0.DX2F	USIC1_CH1.DX0F			ERU1.1A1

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs										
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P3.2	BCCU0.OUT2	USIC1_CH1.SCLKOUT		LEDTS2.COL1	CCU80.OUT11	ACMP2.OUT	USIC1_CH0.SCLKOUT	CCU81.OUT11	CCU41.OUT2							USIC1_CH0.DX3C	USIC1_CH0.DX4C	USIC1_CH1.DX3D	USIC1_CH1.DX4D		ERU1.2A1
P3.3	BCCU0.OUT5	USIC1_CH0.DOUT0		LEDTS2.COL2	CCU80.OUT10	ACMP0.OUT	USIC1_CH1.SELO0	CCU81.OUT10	CCU41.OUT3							USIC1_CH0.DX0E			USIC1_CH1.DX2A		ERU1.1A3
P3.4	BCCU0.OUT6	USIC1_CH0.DOUT0	USIC1_CH0.SCLKOUT	LEDTS2.COL3	CCU80.OUT01	USIC1_CH1.MCLKOUT	USIC1_CH1.SELO1	CCU81.OUT01								USIC1_CH0.DX0F	USIC1_CH0.DX1E		USIC1_CH1.DX2B		ERU1.2A3
P4.0	BCCU0.OUT0	ERU1.PDOUT0	LEDTS2.COL5	ERU1.GOUT0	CCU40.OUT0	ACMP1.OUT	USIC1_CH1.SELO1	CCU81.OUT10	CCU41.OUT0		CCU40.IN0BA	CCU41.IN0AC	CCU80.IN0AU			USIC1_CH0.DX3D	USIC1_CH0.DX4D				
P4.1	BCCU0.OUT8	ERU1.PDOUT1	LEDTS2.COL4	ERU1.GOUT1	CCU40.OUT1	ACMP3.OUT	USIC1_CH1.SELO2	CCU81.OUT11	CCU41.OUT1		CCU40.IN1BA	CCU41.IN1AC	CCU80.IN1AU		POSIF1.IN0B	USIC1_CH0.DX5C					
P4.2	BCCU0.OUT4	ERU1.PDOUT2	CCU81.OUT20	ERU1.GOUT2	CCU40.OUT2	ACMP2.OUT	USIC1_CH1.SELO3	CCU81.OUT12	CCU41.OUT2		CCU40.IN2BA	CCU41.IN2AC	CCU80.IN2AU	CCU81.IN1AB	POSIF1.IN1B	USIC1_CH0.DX5D					
P4.3	BCCU0.OUT5	ERU1.PDOUT3	CCU81.OUT21	ERU1.GOUT3	CCU40.OUT3	ACMP0.OUT	USIC1_CH0.SCLKOUT	CCU81.OUT13	CCU41.OUT3		CCU40.IN3BA	CCU41.IN3AC	CCU80.IN3AU		POSIF1.IN2B		USIC1_CH0.DX1B				
P4.4	BCCU0.OUT0	LEDTS2.LINE0		LEDTS1.COLA	CCU80.OUT00	USIC1_CH0.DOUT0		CCU81.OUT00	CCU41.OUT0			CCU41.IN0AV				USIC1_CH0.DX0C		USIC1_CH1.DX5F			ERU1.0A2
P4.5	BCCU0.OUT8	LEDTS2.LINE1		LEDTS1.COL6	CCU80.OUT01	USIC1_CH0.DOUT0	USIC1_CH0.SCLKOUT	CCU81.OUT01	CCU41.OUT1			CCU41.IN1AV				USIC1_CH0.DX0D	USIC1_CH0.DX1C				ERU1.1A2
P4.6	BCCU0.OUT2	LEDTS2.LINE2	CCU81.OUT10	LEDTS1.COL5	CCU80.OUT10		USIC1_CH0.SCLKOUT	CCU81.OUT02	CCU41.OUT2			CCU41.IN2AV		CCU81.IN0AB			USIC1_CH0.DX1D				ERU1.2A2
P4.7	BCCU0.OUT5	LEDTS2.LINE3	CCU81.OUT11	LEDTS1.COL4	CCU80.OUT11		USIC1_CH0.SELO0	CCU81.OUT03	CCU41.OUT3			CCU41.IN3AV					USIC1_CH0.DX2A				ERU1.0A3
P4.8	BCCU0.OUT7	LEDTS2.LINE4	LEDTS2.COL3	LEDTS1.COL3	CCU80.OUT30	CCU40.OUT0	USIC1_CH0.SELO1	CCU81.OUT30	CAN.N1_TXD		CCU40.IN0AV	CCU41.IN0BA					USIC1_CH0.DX2B			CAN.N1_RXDC	
P4.9	BCCU0.OUT3	LEDTS2.LINE5	LEDTS2.COL2	LEDTS1.COL2	CCU80.OUT31	CCU40.OUT1	USIC1_CH0.SELO2	CCU81.OUT31	CAN.N1_TXD		CCU40.IN1AV	CCU41.IN1BA					USIC1_CH0.DX2C			CAN.N1_RXDD	

Table 9 Port I/O Functions (cont'd)

Function	Outputs									Inputs										
	ALT1	ALT2	ALT3	ALT4	ALT5	ALT6	ALT7	ALT8	ALT9	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input	Input
P4.10		LEDTS2.LINE6	LEDTS2.COL1	LEDTS1.COL1	CCU80.OUT00	CCU40.OUT2	USIC1_CH0.SELO3	CCU81.OUT32	CCU81.OUT00	BCCU0.TRAPIND	CCU40.IN2AV	CCU41.IN2BA		CCU81.IN3AB			USIC1_CH0.DX2D	USIC1_CH1.DX5A			
P4.11		LEDTS2.LINE7	LEDTS2.COL0	LEDTS1.COL0	CCU80.OUT01	CCU40.OUT3	USIC1_CH0.SELO4	CCU81.OUT33	CCU81.OUT01		CCU40.IN3AV	CCU41.IN3BA					USIC1_CH0.DX2E	USIC1_CH1.DX3A	USIC1_CH1.DX4A		

Table 10 Hardware I/O Controlled Functions

Function	Outputs	Outputs	Inputs	Inputs	Pull Control	Pull Control	Pull Control	Pull Control
	HWO0	HWO1	HWI0	HWI1	HW0_PD	HW0_PU	HW1_PD	HW1_PU
P1.3		USIC0_CH0.DOUT3		USIC0_CH0.HWIN3	$\overline{\text{BCCU0.OUT5}}$	BCCU0.OUT5		
P1.4					$\overline{\text{BCCU0.OUT6}}$	BCCU0.OUT6		
P1.5					$\overline{\text{BCCU0.OUT7}}$	BCCU0.OUT7		
P1.6					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8		
P1.7								
P1.8								
P2.0					$\overline{\text{BCCU0.OUT1}}$	BCCU0.OUT1		
P2.1					$\overline{\text{BCCU0.OUT6}}$	BCCU0.OUT6		
P2.2					$\overline{\text{BCCU0.OUT0}}$	BCCU0.OUT0	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.3					$\overline{\text{ACMP2.OUT}}$	ACMP2.OUT		
P2.4					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8		
P2.5					$\overline{\text{ACMP1.OUT}}$	ACMP1.OUT		
P2.6					$\overline{\text{BCCU0.OUT2}}$	BCCU0.OUT2	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.7					$\overline{\text{BCCU0.OUT8}}$	BCCU0.OUT8	$\overline{\text{CCU40.OUT3}}$	CCU40.OUT3
P2.8					$\overline{\text{BCCU0.OUT1}}$	BCCU0.OUT1	$\overline{\text{CCU40.OUT2}}$	CCU40.OUT2
P2.9					$\overline{\text{BCCU0.OUT7}}$	BCCU0.OUT7	$\overline{\text{CCU40.OUT2}}$	CCU40.OUT2
P2.10					$\overline{\text{BCCU0.OUT4}}$	BCCU0.OUT4		
P2.11					$\overline{\text{BCCU0.OUT5}}$	BCCU0.OUT5		
P2.12					$\overline{\text{BCCU0.OUT3}}$	BCCU0.OUT3	$\overline{\text{CCU41.OUT0}}$	CCU41.OUT0
P2.13					$\overline{\text{BCCU0.OUT4}}$	BCCU0.OUT4	$\overline{\text{CCU41.OUT2}}$	CCU41.OUT2
P3.0								
P3.1		USIC1_CH0.DOUT3		USIC1_CH0.HWIN3				
P3.2		USIC1_CH0.DOUT2		USIC1_CH0.HWIN2				
P3.3		USIC1_CH0.DOUT1		USIC1_CH0.HWIN1				
P3.4		USIC1_CH0.DOUT0		USIC1_CH0.HWIN0				
P4.0								
P4.1								
P4.2								
P4.3								

3.1.2 Absolute Maximum Ratings

Stresses above the values listed under “Absolute Maximum Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.

Table 11 Absolute Maximum Rating Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Junction temperature	T_J	SR	-40	–	115	°C	–
Storage temperature	T_{ST}	SR	-40	–	125	°C	–
Voltage on power supply pin with respect to V_{SSP}	V_{DDP}	SR	-0.3	–	6	V	–
Voltage on digital pins with respect to V_{SSP} [1]	V_{IN}	SR	-0.5	–	V_{DDP} + 0.5 or max. 6	V	whichever is lower
Voltage on P2 pins with respect to V_{SSP} [2]	V_{INP2}	SR	-0.3	–	V_{DDP} + 0.3	V	–
Voltage on analog input pins with respect to V_{SSP}	V_{AIN} V_{AREF}	SR	-0.5	–	V_{DDP} + 0.5 or max. 6	V	whichever is lower
Input current on any pin during overload condition	I_{IN}	SR	-10	–	10	mA	–
Absolute maximum sum of all input currents during overload condition	ΣI_{IN}	SR	-50	–	+50	mA	–

1) Excluding port pins P2.[1,2,6,7,8,9,11].

2) Applicable to port pins P2.[1,2,6,7,8,9,11].

3.1.4 Operating Conditions

The following operating conditions must not be exceeded in order to ensure correct operation and reliability of the XMC1400. All parameters specified in the following tables refer to these operating conditions, unless noted otherwise.

Table 15 Operating Conditions Parameters

Parameter	Symbol		Values			Unit	Note / Test Condition
			Min.	Typ.	Max.		
Ambient Temperature	T_A	SR	-40	–	85	°C	Temp. Range F
			-40	–	105	°C	Temp. Range X
Digital supply voltage[1)]	V_{DDP}	SR	1.8	–	5.5	V	
Short circuit current of digital outputs	I_{SC}	SR	-5	–	5	mA	
Absolute sum of short circuit currents of the device	ΣI_{SC_D}	SR	–	–	25	mA	

1) See also the Supply Monitoring thresholds, **Chapter 3.3.2**.

3.2 DC Parameters

3.2.1 Input/Output Characteristics

Table 16 provides the characteristics of the input/output pins of the XMC1400.

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Note: Unless otherwise stated, input DC and AC characteristics, including peripheral timings, assume that the input pads operate with the standard hysteresis.

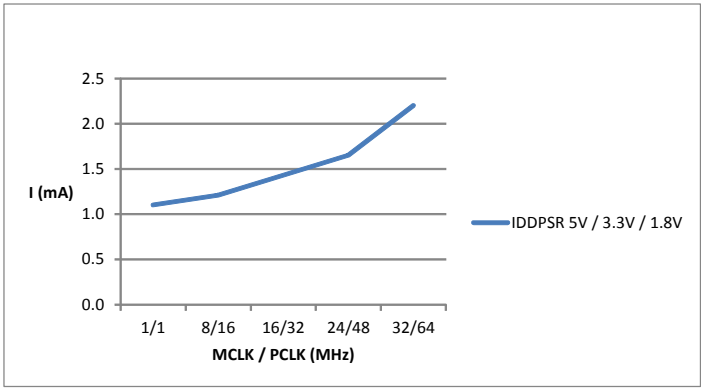
Table 16 Input/Output Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Output low voltage on port pins (with standard pads)	V_{OLP}	CC	–	1.0	V	I_{OL} = 11 mA (5 V) I_{OL} = 7 mA (3.3 V)
			–	0.4	V	I_{OL} = 5 mA (5 V) I_{OL} = 3.5 mA (3.3 V)
Output low voltage on high current pads	V_{OLP1}	CC	–	1.0	V	I_{OL} = 50 mA (5 V) I_{OL} = 25 mA (3.3 V)
			–	0.32	V	I_{OL} = 10 mA (5 V)
			–	0.4	V	I_{OL} = 5 mA (3.3 V)
Output high voltage on port pins (with standard pads)	V_{OHP}	CC	V_{DDP} - 1.0	–	V	I_{OH} = -10 mA (5 V) I_{OH} = -7 mA (3.3 V)
			V_{DDP} - 0.4	–	V	I_{OH} = -4.5 mA (5 V) I_{OH} = -2.5 mA (3.3 V)
Output high voltage on high current pads	V_{OHP1}	CC	V_{DDP} - 0.32	–	V	I_{OH} = -6 mA (5 V)
			V_{DDP} - 1.0	–	V	I_{OH} = -8 mA (3.3 V)
			V_{DDP} - 0.4	–	V	I_{OH} = -4 mA (3.3 V)
Input low voltage on port pins (Standard Hysteresis)	V_{ILPS}	SR	–	0.19 × V_{DDP}	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Input high voltage on port pins (Standard Hysteresis)	V_{IHPS}	SR	0.7 × V_{DDP}	–	V	CMOS Mode (5 V, 3.3 V & 2.2 V)

Table 16 Input/Output Characteristics (Operating Conditions apply) (cont'd)

Parameter	Symbol		Limit Values		Unit	Test Conditions
			Min.	Max.		
Input low voltage on port pins (Large Hysteresis)	V_{ILPL}	SR	–	0.08 × V_{DDP}	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Input high voltage on port pins (Large Hysteresis)	V_{IHPL}	SR	0.85 × V_{DDP}	–	V	CMOS Mode (5 V, 3.3 V & 2.2 V)
Rise/fall time on High Current Pad[1)]	t_{HCPR}, t_{HCPF}	CC	–	9	ns	50 pF @ 5 V[2)]
			–	12	ns	50 pF @ 3.3 V[3)]
			–	25	ns	50 pF @ 1.8 V[4)]
Rise/fall time on Standard Pad[1)]	t_R, t_F	CC	–	12	ns	50 pF @ 5 V[5)]
			–	15	ns	50 pF @ 3.3 V[6)].
			–	31	ns	50 pF @ 1.8 V[7)].
Input Hysteresis on port pin except P2.3 - P2.9[8)]	HYS	CC	0.08 × V_{DDP}	–	V	CMOS Mode (5 V), Standard Hysteresis
			0.03 × V_{DDP}	–	V	CMOS Mode (3.3 V), Standard Hysteresis
			0.02 × V_{DDP}	–	V	CMOS Mode (2.2 V), Standard Hysteresis
			0.5 × V_{DDP}	0.75 × V_{DDP}	V	CMOS Mode(5 V), Large Hysteresis
			0.4 × V_{DDP}	0.75 × V_{DDP}	V	CMOS Mode(3.3 V), Large Hysteresis
			0.2 × V_{DDP}	0.65 × V_{DDP}	V	CMOS Mode(2.2 V), Large Hysteresis

Figure 18 shows typical graphs for sleep mode current for V_{DDP} = 5 V, V_{DDP} = 3.3 V, V_{DDP} = 1.8 V across different clock frequencies.



Condition:
1. TA = +25° C

Figure 18 Sleep mode, peripherals clocks disabled, Flash powered down: Supply current I_{DDPSD} over supply voltage V_{DDP} for different clock frequencies

3.3.4 Serial Wire Debug Port (SW-DP) Timing

The following parameters are applicable for communication through the SW-DP interface.

Note: These parameters are not subject to production test, but verified by design and/or characterization.

Table 29 SWD Interface Timing Parameters(Operating Conditions apply)

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
SWDCLK high time	t_1 SR	50	–	500000	ns	–
SWDCLK low time	t_2 SR	50	–	500000	ns	–
SWDIO input setup to SWDCLK rising edge	t_3 SR	10	–	–	ns	–
SWDIO input hold after SWDCLK rising edge	t_4 SR	10	–	–	ns	–
SWDIO output valid time after SWDCLK rising edge	t_5 CC	–	–	68	ns	C_L = 50 pF
		–	–	62	ns	C_L = 30 pF
SWDIO output hold time from SWDCLK rising edge	t_6 CC	4	–	–	ns	

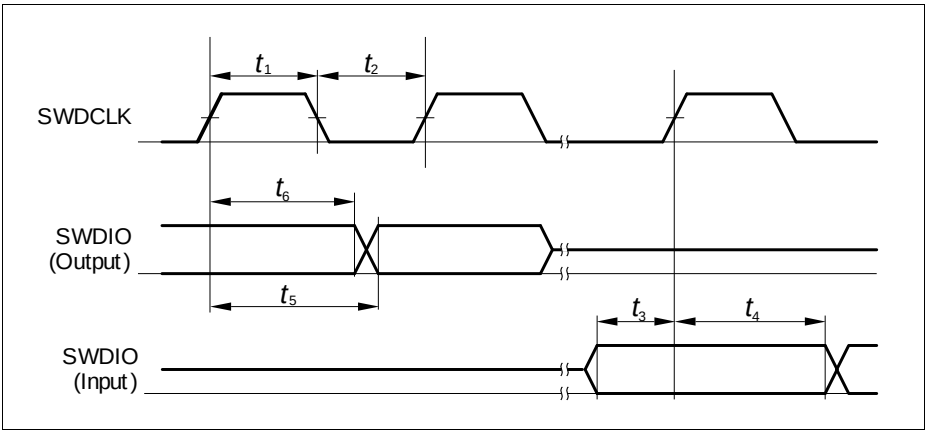


Figure 24 SWD Timing

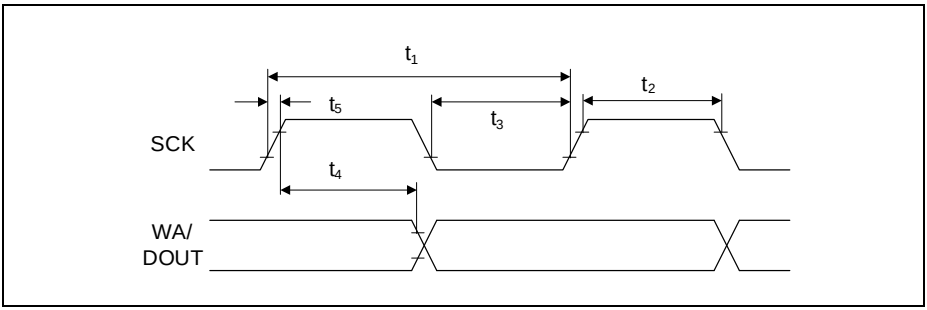


Figure 27 USIC IIS Master Transmitter Timing

Table 36 USIC IIS Slave Receiver Timing

Parameter	Symbol	Values			Unit	Note / Test Condition
		Min.	Typ.	Max.		
Clock period	t_6 SR	$4/f_{MCLK}$	-	-	ns	
Clock HIGH	t_7 SR	0.35 x t_{6min}	-	-	ns	
Clock Low	t_8 SR	0.35 x t_{6min}	-	-	ns	
Set-up time	t_9 SR	0.3 x t_{6min}	-	-	ns	
Hold time	t_{10} SR	15	-	-	ns	

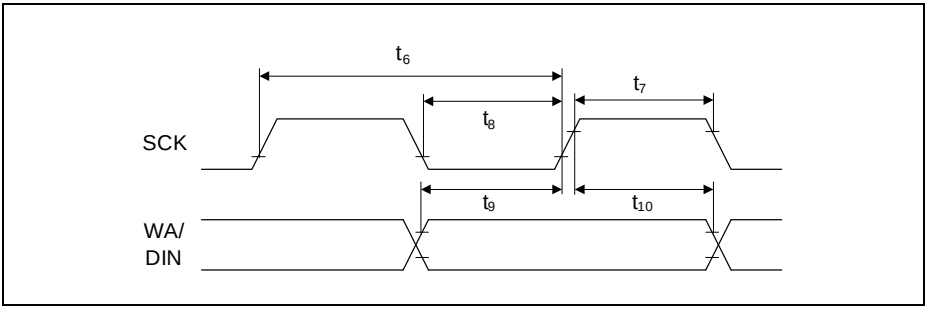


Figure 28 USIC IIS Slave Receiver Timing

4 Package and Reliability

The XMC1400 is a member of the XMC1000 Family of microcontrollers. It is also compatible to a certain extent with members of similar families or subfamilies.

Each package is optimized for the device it houses. Therefore, there may be slight differences between packages of the same pin-count but for different device types. In particular, the size of the exposed die pad may vary.

If different device types are considered or planned for an application, it must be ensured that the board layout fits all packages under consideration.

4.1 Package Parameters

Table 37 provides the thermal characteristics of the packages used in XMC1400.

Table 37 Thermal Characteristics of the Packages

Parameter	Symbol	Limit Values		Unit	Package Types
		Min.	Max.		
Exposed Die Pad Dimensions	Ex × Ey CC	-	3.7 × 3.7	mm	PG-VQFN-40-17
		-	4.2 × 4.2	mm	PG-VQFN-48-73
		-	4.6 × 4.6	mm	PG-VQFN-64-6
Thermal resistance Junction-Ambient	$R_{\Theta JA}$ CC	-	86.0	K/W	PG-TSSOP-38-9[1)]
		-	45.3	K/W	PG-VQFN-40-17[1)]
		-	44.9	K/W	PG-VQFN-48-73[1)]
		-	66.7	K/W	PG-LQFP-64-26[1)]
		-	44.7	K/W	PG-VQFN-64-6[1)]

1) Device mounted on a 4-layer JEDEC board (JESD 51-5); exposed pad soldered.

Note: For electrical reasons, it is required to connect the exposed pad to the board ground V_{SSP}, independent of EMC and thermal requirements.

4.1.1 Thermal Considerations

When operating the XMC1400 in a system, the total heat generated in the chip must be dissipated to the ambient environment to prevent overheating and the resulting thermal damage.

The maximum heat that can be dissipated depends on the package and its integration into the target board. The “Thermal resistance $R_{\Theta JA}$” quantifies these parameters. The power dissipation must be limited so that the average junction temperature does not exceed 115 °C.

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